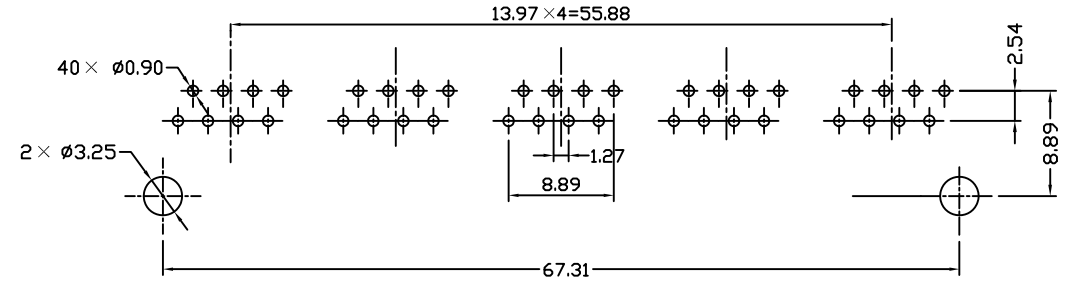
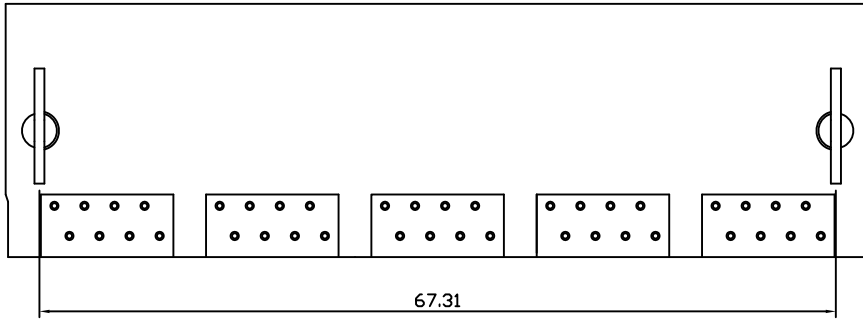
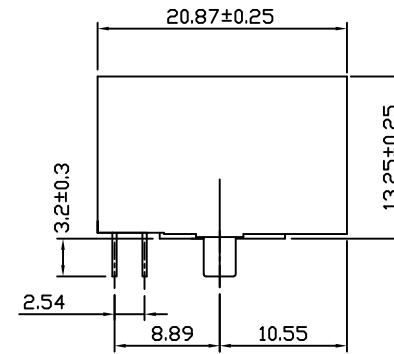
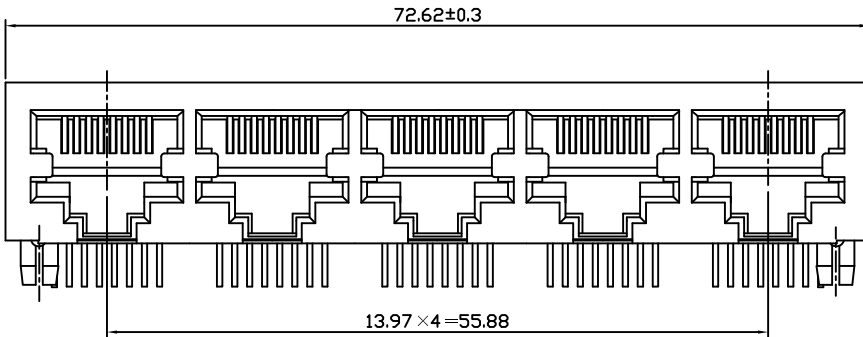


Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/09/26	



PC Board Layout (Top View)



PCB JACK Specification

1. Insulation Resistance: 500MΩ MIN @ 500 VDC
2. Withstanding Voltage: AC1000V 50Hz or 60Hz 1min.
3. Durability: 600 Mating Circles MIN.
4. Gold Plating: Gold Flash.
5. (1) Storage: -40°C to +85°C
(2) Operation: -40°C to +85°C
(3) Wave solder temperature: 230°C to 250°C, 5~10 Sec.

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.25	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: RJ45 1×5 CONNECTOR
ANGLES ±1°	UNIT: mm	PART NO.: LPEF1050NNL
	SCALE: 2/1	SHEET: 1/1
	REV: A	DWG NO.: LP11092616